

HEXFRED® Ultrafast Soft Recovery Diode, 140 A



PRODUCT SUMMARY				
V_{R}	1200 V			
V _F (typical)	2.8 V			
t _{rr} (typical)	48 ns			
I _{F(DC)} at T _C , per module	140 A at 74 °C			
I _{F(AV)} at T _C , per module	140 A at 46 °C			
Package	SOT-227			

FEATURES

- · Fast recovery time characteristic
- Electrically isolated base plate
- Large creepage distance between terminal
- · Simplified mechanical designs, rapid assembly
- · Designed and qualified for industrial level
- UL approved file E78996
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION/APPLICATIONS

The dual diode series configuration VS-HFA140FA120 is used for output rectification or freewheeling/clamping operation and high voltage application.

The semiconductor in the SOT-227 package is isolated from the copper base plate, allowing for common heatsinks and compact assemblies to be built.

These modules are intended for general applications such as HV power supplies, electronic welders, motor control and inverters.

ABSOLUTE MAXIMUM RATINGS						
PARAMETER		SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Cathode to anode voltage		V_{R}		1200	V	
per leg			T 74.00	70		
Continuous forward current	per module	e I _F	T _C = 74 °C	140	Α	
Single pulse forward current		I _{FSM}	T _J = 25 °C	350	i	
Maximum power dissipation, per leg		P _D	T _C = 25 °C	357	W	
			T _C = 100 °C	143] vv	
RMS isolation voltage		V _{ISOL}	Any terminal to case, t = 1 minute	2500	V	
Operating junction and storage range	temperature	T _J , T _{Stg}		- 55 to + 150	°C	

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	YMBOL TEST CONDITIONS		TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	I _R = 100 μA	1200	-	-	
Forward voltage, per leg	V _{FM}	I _F = 60 A	-	2.8	4.0	
		I _F = 120 A	-	3.6	5.3	V
		I _F = 60 A, T _J = 125 °C	-	2.7	-	
		I _F = 60 A, T _J = 150 °C	-	2.65	-	
	I _{RM}	V _R = V _R rated	-	2.0	75	μΑ
Reverse leakage current, per leg		T _J = 125 °C, V _R = V _R rated	-	1.6	5	A
		T _J = 150 °C, V _R = V _R rated	-	5	10	- mA



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
		$I_F = 1 \text{ A}; dI_F/dt = 200 \text{ A/}\mu\text{s}; V_R = 30 \text{ V}$		1	48	1	
Reverse recovery time, per leg	t _{rr}	T _J = 25 °C	I _F = 50 A dI _F /dt = - 200 A/μs V _R = 200 V	-	145	-	ns
		T _J = 125 °C		-	218	-	
	I _{RRM}	T _J = 25 °C		-	13	-	А
Peak recovery current, per leg		T _J = 125 °C		-	18	-	
Reverse recovery charge, per leg	Q _{rr}	T _J = 25 °C		-	910	-	nC
		T _J = 125 °C		-	1920	-	iiC
Junction capacitance, per leg	C _T	V _R = 1200 V		-	27	-	pF

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Junction to case, single leg conducting	В		-	-	0.35	
Junction to case, both legs conducting	R _{thJC}		-	-	0.175	°C/W
Case to heatsink	R _{thCS}	Flat, greased surface	-	0.05	-	
Weight			-	30	-	g
Mounting torque			-	-	1.3	Nm
Case style				SOT	-227	



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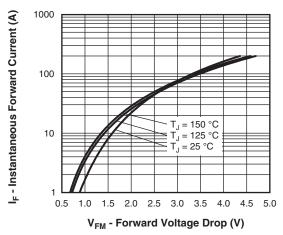


Fig. 1 - Typical Forward Voltage Drop Characteristics

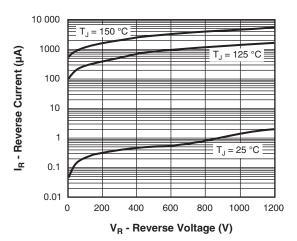


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

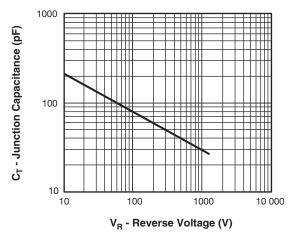


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

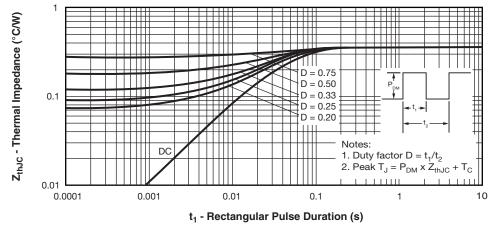


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)



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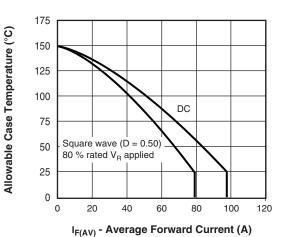


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

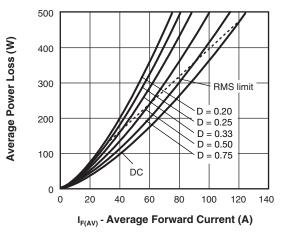


Fig. 6 - Forward Power Loss Characteristics

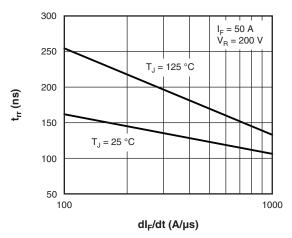


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

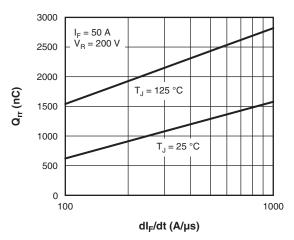


Fig. 8 - Typical Stored Charge vs. dl_F/dt

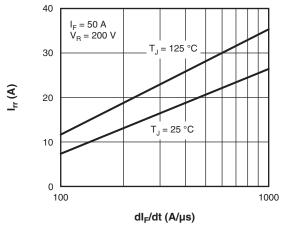


Fig. 9 - Typical Peak Recovery Current vs. dl_F/dt

Note

(1) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{th,JC}$; $Pd = Forward power loss = I_{F(AV)} \times V_{FM} at (I_{F(AV)}/D)$ (see fig. 5); $Pd_{REV} = Inverse power loss = V_{R1} \times I_R (1 - D)$; I_R at $V_{R1} = Rated V_R$

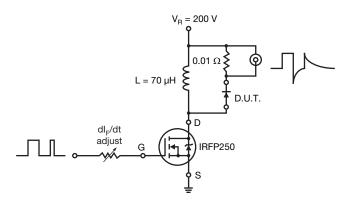
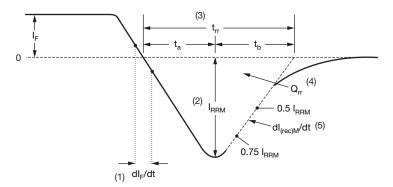


Fig. 10 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

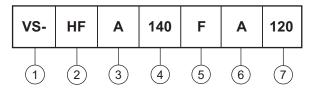
$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 11 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code



- Vishay Semiconductors product
- 2 HEXFRED® family
- Process designator (A = Electron irradiated)
- **4** Average current (140 = 140 A)
- 5 Circuit configuration (2 separate diodes, parallel pin-out)
- 6 Package indicator (SOT-227 standard insulated base)
- 7 Voltage rating (120 = 1200 V)

CIRCUIT CONFIGURATION					
CIRCUIT	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING			
2 separate diodes, parallel pin-out	F	Lead Assignment 4			

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95423			
Part marking information	www.vishay.com/doc?95425			



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